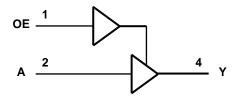


### **Pin Descriptions**

Pin Name	Description				
OE	Output Enable (active high)				
А	Data Input				
GND	Ground				
Y	Data Output				
Vcc	Supply Voltage				

## **Logic Diagram**



### **Function Table**

Inp	uts	Output		
OE	OE A			
Н	Н	Н		
Н	L	L		
L	Х	Z		



### **Absolute Maximum Ratings (Note 3)**

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	KV
ESD MM	Machine Model ESD Protection	200	٧
V <sub>CC</sub>	Supply Voltage Range	-0.5 to 6.5	V
VI	Input Voltage Range	-0.5 to 6.5	٧
Vo	Voltage applied to output in high impedance or I <sub>OFF</sub> state	-0.5 to 6.5	٧
Vo	Voltage applied to output in high or low state	-0.3 to V <sub>CC</sub> +0.5	V
I <sub>IK</sub>	Input Clamp Current V <sub>I</sub> <0	-50	mA
I <sub>OK</sub>	Output Clamp Current	-50	mA
Io	Continuous output current	±50	mA
	Continuous current through Vdd or GND	±100	mA
TJ	Operating Junction Temperature	-40 to 150	°C
T <sub>STG</sub>	Storage Temperature	-65 to 150	°C

Note: 3. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.



# **Recommended Operating Conditions (Note 4)**

Symbol		Parameter	Min	Max	Unit	
.,	On a ratio a Valta sa	Operating	1.4	5.5	V	
V <sub>cc</sub>	Operating Voltage	Data retention only	1.2		V	
	High Level Input Voltage	V <sub>CC</sub> = 1.4 V to 1.95 V	0.65 X V <sub>CC</sub>			
\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \		V <sub>CC</sub> = 2.3 V to 2.7 V	1.7		V	
V <sub>IH</sub>	High Level Input voltage	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$	2		V	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	0.7 X V <sub>CC</sub>			
		V <sub>CC</sub> = 1.4 V to 1.95 V		0.35 X V <sub>CC</sub>		
V <sub>IL</sub>	Low Level Input Voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V	
V IL	Low Level Input Voltage	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		0.8	V	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		0.3 X V <sub>CC</sub>		
VI	Input Voltage		0	5.5	V	
Vo	Output Voltage		0	V <sub>CC</sub>	V	
	, High Level Output	Vcc=1.4 V		-3		
		V <sub>CC</sub> = 1.65 V		-4		
		$V_{CC} = 2.3 \text{ V}$		-8	mA	
I <sub>OH</sub>	Current	$V_{CC} = 3 \text{ V}$		-16	ША	
		V <sub>CC</sub> = 3 V		-24		
		$V_{CC} = 4.5 \text{ V}$		-32		
		Vcc=1.4 V		3		
		V <sub>CC</sub> = 1.65 V		4		
	Low Level Output	$V_{CC} = 2.3 \text{ V}$		8	mΑ	
I <sub>OL</sub>	Current	$V_{CC} = 3 \text{ V}$		16		
		V <sub>CC</sub> = 3 V		24		
		$V_{CC} = 4.5 \text{ V}$		32		
	Land Charles 200	V <sub>CC</sub> = 1.4 to 3V		20		
Δt/ΔV	Input transition rise or fall rate	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		10	ns/V	
	iale	$V_{CC} = 5 \text{ V} \pm 0.5 \text{ V}$		5		
T <sub>A</sub>	Operating free-air temperature		-40	85	°С	

Note: 4. Unused inputs should be held at Vcc or Ground.



### Electrical Characteristics (All typical values are at Vcc = 3.3V, T<sub>A</sub> = 25°C)

Over recommended free-air temperature range (unless otherwise noted)

Symbol	Parameter	Test Conditions	Vcc	Min	Тур.	Max	Unit
		$I_{OH} = -100 \mu A$	1.4 V to 5.5V	V <sub>CC</sub> - 0.1			
		$I_{OH} = -3mA$	1.4 V	1.05			
		$I_{OH} = -4mA$	1.65 V	1.2			
$V_{OH}$	High Level Output Voltage	$I_{OH} = -8mA$	2.3V	1.9			V
	Voltage	$I_{OH} = -16mA$	3 V	2.4			
		$I_{OH} = -24mA$	3 V	2.3			
		$I_{OH} = -32mA$	4.5 V	3.8			
		$I_{OL} = 100 \mu A$	1.4 V to 5.5V			0.1	
		$I_{OL} = 3mA$	1.4V			.4	
	1 - 1 - 10 (- 1	$I_{OL} = 4mA$	1.65 V			0.45	
$V_{OL}$	Low Level Output Voltage	$I_{OL} = 8mA$	2.3V			0.3	V
	venage	$I_{OL} = 16mA$	3 V			0.4	
		$I_{OL} = 24mA$	3 V			0.55	
		$I_{OL} = 32mA$	4.5			0.55	
I <sub>I</sub>	Input Current	$V_1 = 5.5 \text{ V or GND}$	0 to 5.5 V			± 5	μΑ
I <sub>OFF</sub>	Power Down Leakage Current	$V_1$ or $V_0 = 5.5V$	0			± 10	μA
l <sub>oz</sub>	Z State Leakage Current	V <sub>O</sub> =0 to 5.5V	3.6V			10	μΑ
I <sub>cc</sub>	Supply Current	$V_1 = 5.5V$ of GND $I_0=0$	1.4 V to 5.5V			10	μΑ
Δl <sub>CC</sub>	Additional Supply Current	One input at V <sub>CC</sub> – 0.6 V Other inputs at V <sub>CC</sub> or GND	3 V to 5.5V			500	μA
$C_{i}$	Input Capacitance	$V_i = V_{CC} - \text{ or GND}$	3.3		3.5		pF
	The second Description	SOT25	(Note 5)		204		
$\theta_{JA}$	Thermal Resistance Junction-to-Ambient	SOT353	(Note 5)		371		°C/W
	Canolion to Ambient	DFN1410	(Note 5)		430		
	The survey Decisters in	SOT25	(Note 5)		52		
$\theta_{\text{JC}}$	Thermal Resistance Junction-to-Case	SOT353	(Note 5)		143		°C/W
	Junction-to-Case	DFN1410	(Note 5)		190		

Note: 5. Test condition for SOT25, SOT353 and DFN1410: Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.



### **Switching Characteristics**

Over recommended free-air temperature range, CL = 15pF (see Figure 1)

Parameter	From	то	Vcc = ± 0			: 1.8 V .15V		: 2.5 V ).2V		3.3 V 3.3V		= 5 V ).5V	Unit
	(Input)	(OUTPUT)	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
t <sub>pd</sub>	Α	Y	1.7	6.9	1.1	4.8	0.4	3.6	0.4	3	0.4	3	ns

Over recommended free-air temperature range, CL = 30 or 50pF as noted (see Figure 2)

Parameter	From	то	Vcc = ± 0			: 1.8 V .15V		: 2.5 V ).2V		: 3.3 V ).3V		= 5 V ).5V	Unit
	(Input)	(OUTPUT)	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
t <sub>pd</sub>	Α	Y	2.6	8	1.8	5.6	0.8	4.4	0.8	3.6	0.9	3.6	ns
t <sub>en</sub>	ŌE	Υ	2.8	9.4	1.9	6.5	1	5.2	0.9	4.3	0.9	4.3	
t <sub>dis</sub>	OE	Y	1.6	9.8	1.1	6.8	0.8	4.4	0.8	4.5	0.9	3.7	

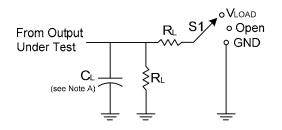
## **Operating Characteristics**

 $T_A = 25$  °C

	Parameter		Test	Vcc = 1.5 V	Vcc = 1.8 V	Vcc = 2.5 V	Vcc = 3.3 V	Vcc = 5 V	Unit
			Conditions	TYP	TYP	TYP	TYP	TYP	
	Power dissipation	Outputs enabled	f = 10 MHz	19	19	19	19	19	pF
C <sub>pd</sub>	capacitance	Outputs disabled	1 = 10 101112	2	2	2	3	4	рг

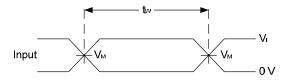


#### **Parameter Measurement Information**

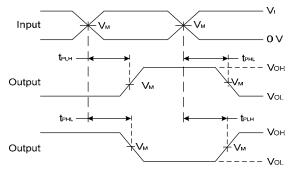


TEST	S1
t <sub>PLH</sub> /t <sub>PHL</sub>	Open
t <sub>PLZ</sub> /t <sub>PZL</sub>	Vload
t <sub>PHZ</sub> /t <sub>PZH</sub>	GND

Vcc	In	puts	V	0.	D.	
VCC	Vı	t <sub>r</sub> /t <sub>f</sub>	· V <sub>M</sub>	CL	$R_{L}$	
1.5V±0.1V	V <sub>CC</sub>	≤2ns	V <sub>CC</sub> /2	15pF	1ΜΩ	
1.8V±0.15V	V <sub>CC</sub>	≤2ns	V <sub>CC</sub> /2	15pF	1ΜΩ	
2.5V±0.2V	V <sub>cc</sub>	≤2ns	V <sub>CC</sub> /2	15pF	1ΜΩ	
3.3V±0.3V	3V	≤2.5ns	1.5V	15pF	1ΜΩ	
5V±0.5V	V <sub>CC</sub>	≤2.5ns	V <sub>CC</sub> /2	15pF	1ΜΩ	



#### **Voltage Waveform Pulse Duration**



Voltage Waveform Propagation Delay Times Inverting and Non Inverting Outputs

Output
Control

Output
Waveform 1
S1 at V<sub>LOAD</sub>
(see Note B)

Output
Waveform 2
S1 at GND
(see Note B)

Output

V<sub>M</sub>

V<sub></sub>

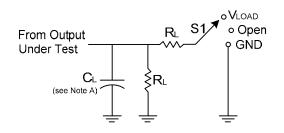
Voltage Waveform Enable and Disable Times
Low and High Level Enabling

- Notes: A. Includes test lead and test apparatus capacitance.
  - B. All pulses are supplied at pulse repetition rate ≤ 10 MHz.
  - C. Inputs are measured separately one transition per measurement.
  - D.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis.}$
  - E.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{EN}$ .
  - F. t<sub>PLH</sub> and t<sub>PHL</sub> are the same as t<sub>PD.</sub>

Figure 1. Load Circuit and Voltage Waveforms

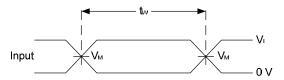


#### **Parameter Measurement Information (Continued)**

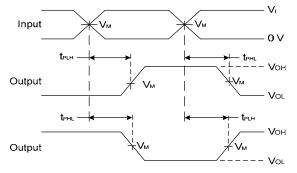


TEST	S1
t <sub>PLH</sub> /t <sub>PHL</sub>	Open
$t_{PLZ}/t_{PZL}$	Vload
t <sub>PHZ</sub> /t <sub>PZH</sub>	GND

Vcc	Inj	outs	V <sub>M</sub>	CL	RL
	Vi	t <sub>r</sub> /t <sub>f</sub>	- IVI	OL.	
1.5V±0.1V	V <sub>cc</sub>	≤2ns	V <sub>CC</sub> /2	30pF	1ΚΩ
1.8V±0.15V	V <sub>cc</sub>	≤2ns	V <sub>CC</sub> /2	30pF	1ΚΩ
2.5V±0.2V	V <sub>cc</sub>	≤2ns	V <sub>CC</sub> /2	30pF	500Ω
3.3V±0.3V	3V	≤2.5ns	1.5V	50pF	500Ω
5V±0.5V	V <sub>CC</sub>	≤2.5ns	V <sub>CC</sub> /2	50pF	500Ω



#### **Voltage Waveform Pulse Duration**



Voltage Waveform Propagation Delay Times Inverting and Non Inverting Outputs

Output
Control

Output
Waveform 1
S1 at V<sub>LOAD</sub>
(see Note B)

Output
Waveform 2
S1 at GND
(see Note B)

V<sub>M</sub>

Voltage Waveform Enable and Disable Times Low and High Level Enabling

Notes: A. Includes test lead and test apparatus capacitance.

- B. All pulses are supplied at pulse repetition rate ≤ 10 MHz.
- C. Inputs are measured separately one transition per measurement.
- D.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis.}$
- E.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{EN0}$
- F.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{PD.}$

Figure 2. Load Circuit and Voltage Waveforms



### **Ordering Information**

T4LVCE1G 126 XXX - 7

Logic Device Function Package Packing

74: Logic Prefix 126: 3-State Buffer W5: SOT25 7: Tape & Reel

LVCE : 1.4 to 5.5V OE-High SE : SOT353
Family FZ4 : DFN1410

1G: One gate

	Dovice	Package	Packaging	7" Tape and Reel	
	Device	Code	(Note 5)	Quantity	Part Number Suffix
<b>Pb</b> ,	74LVCE1G126W5-7	W6	SOT25	3000/Tape & Reel	-7
<b>Pb</b> ,	74LVCE1G126SE-7	SE	SOT353	3000/Tape & Reel	-7
<b>Pb</b> ,	74LVCE1G126FZ4-7	FZ4	DFN1410	5000/Tape & Reel	-7

Note: 6. Pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.



### **Marking Information**

#### (1) SOT25 and SOT353

### (Top View)

5 4

2

1

XX Y WX

3

XX : Identification code Y : Year 0~9

 $\underline{W}$  : Week : A $^{\sim}$ Z : 1 $^{\sim}$ 26 week;

a $^z$ : 27 $^5$ 2 week; z represents 52 and 53 week

52 and 53 week X : A~Z : Internal code

Part Number	Package	Identification Code
74LVCE1G126W5	SOT25	PZ
74LVCE1G126SE	SOT353	PZ

#### (2) DFN1410

### (Top View)

XX YWX XX: Identification Code

Y: Year : 0~9

W: Week: A~Z: 1~26 week;

a~z: 27~52 week; z represents

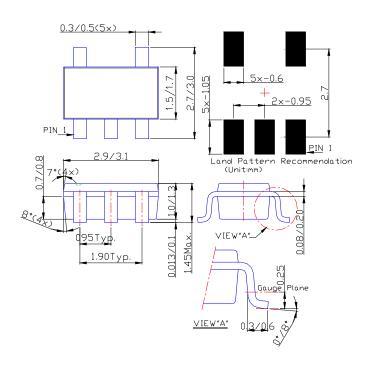
52 and 53 week X: A~Z: Internal code

Part Number	Package	Identification Code
74LVCE1G126FZ4	DFN1410	PZ

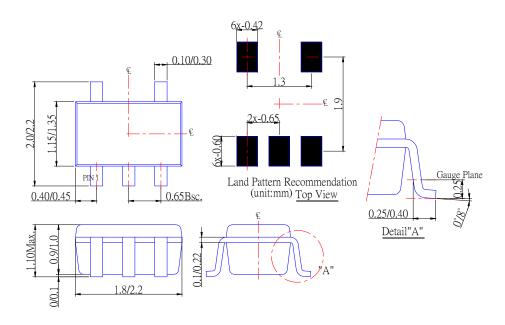


### Package Outline Dimensions (All Dimensions in mm)

#### (1) Package Type: SOT25



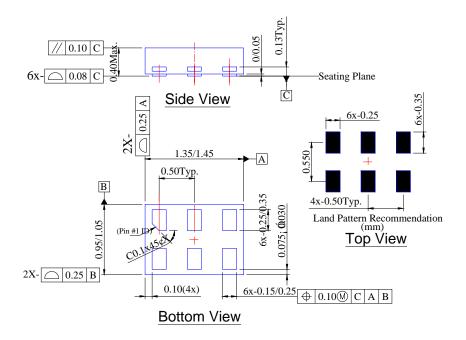
#### (2) Package Type: SOT353





### Package Outline Dimensions (All Dimensions in mm)

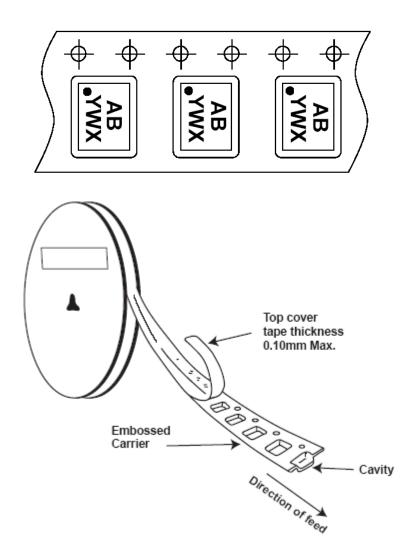
### (3) Package Type: DFN1410





### **Taping Orientation (Note 7)**

#### For DFN1410



Note: 7. The taping orientation of the other package type can be found on our website at http://www.diodes.com/datasheets/ap02007.pdf



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